



## 6A, 800V N-CHANNEL MOSFET

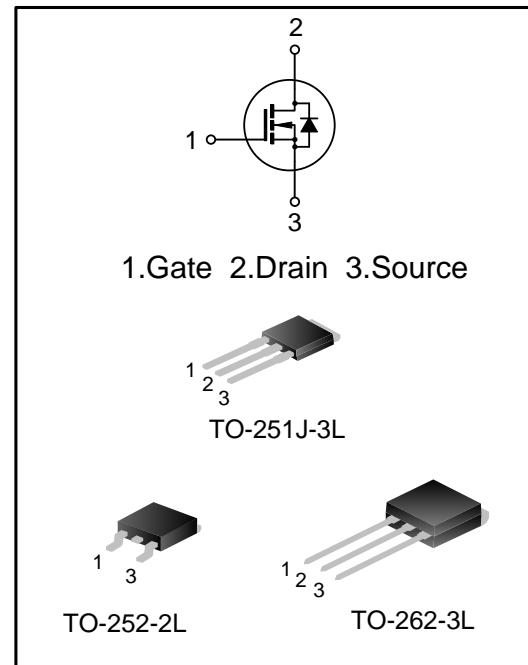
### GENERAL DESCRIPTION

SVF6N80D(K)(MJ) is an N-channel enhancement mode power MOS field effect transistor which is produced using Silan proprietary F-Cell™ high-voltage planar VDMOS technology. The improved process and cell structure have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are widely used in AC-DC power supplies, DC-DC converters and H-bridge PWM motor drivers.

### FEATURES

- 6A,800V,  $R_{DS(on)(typ.)}=2.0\Omega @ V_{GS}=10V$
- Low gate charge
- Low Crss
- Fast switching
- Improved dv/dt capability



### ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing Type
SVF6N80DTR	TO-252-2L	SVF6N80D	Halogen free	Tape&Reel
SVF6N80K	TO-262-3L	SVF6N80K	Pb free	Tube
SVF6N80MJ	TO-251J-3L	SVF6N80MJ	Halogen free	Tube



## ABSOLUTE MAXIMUM RATINGS ( $T_A=25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Ratings		Unit
		SVF6N80D/MJ	SVF6N80K	
Drain-Source Voltage	$V_{DS}$	800		V
Gate-Source Voltage	$V_{GS}$	$\pm 30$		V
Drain Current	$I_D$	6.0		A
		3.9		
Drain Current Pulsed	$I_{DM}$	24		A
Power Dissipation( $T_C=25^\circ\text{C}$ ) -Derate above $25^\circ\text{C}$	$P_D$	132	138	W
		1.06	1.1	W/ $^\circ\text{C}$
Single Pulsed Avalanche Energy(Note 1)	$E_{AS}$	323		mJ
Reverse Diode dv/dt (Note 2)	dv/dt	4.5		V/ns
MOSFET dv/dt Ruggedness (Note 3)	dv/dt	50		V/ns
Operation Junction Temperature Range	$T_J$	$-55\sim+150$		$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	$-55\sim+150$		$^\circ\text{C}$

## THERMAL CHARACTERISTICS

Characteristics	Symbol	Ratings		Unit
		SVF6N80D/MJ	SVF6N80K	
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.95	0.91	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.0	62.5	$^\circ\text{C}/\text{W}$



## ELECTRICAL CHARACTERISTICS (T<sub>J</sub>=25°C UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	800	--	--	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =800V, V <sub>GS</sub> =0V	--	--	1.0	μA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	--	--	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> =250μA	2.0	--	4.0	V
Static Drain- Source On State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =3.0A	--	2.0	2.7	Ω
Input Capacitance	R <sub>g</sub>	f=1.0MHz	--	4.8	--	Ω
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	---	677	---	pF
Output Capacitance	C <sub>oss</sub>		--	71	--	
Reverse Transfer Capacitance	C <sub>rss</sub>		--	4.0	--	
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =400V, I <sub>D</sub> =6.0A, R <sub>G</sub> =25Ω (Note 3,4)	--	12	--	ns
Turn-on Rise Time	t <sub>r</sub>		--	23	--	
Turn-off Delay Time	t <sub>d(off)</sub>		--	25	--	
Turn-off Fall Time	t <sub>f</sub>		--	23	--	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =640V, I <sub>D</sub> =6.0A, V <sub>GS</sub> =10V (Note 3,4)	--	15	--	nC
Gate-Source Charge	Q <sub>gs</sub>		--	4.3	--	
Gate-Drain Charge	Q <sub>gd</sub>		--	6.8	--	

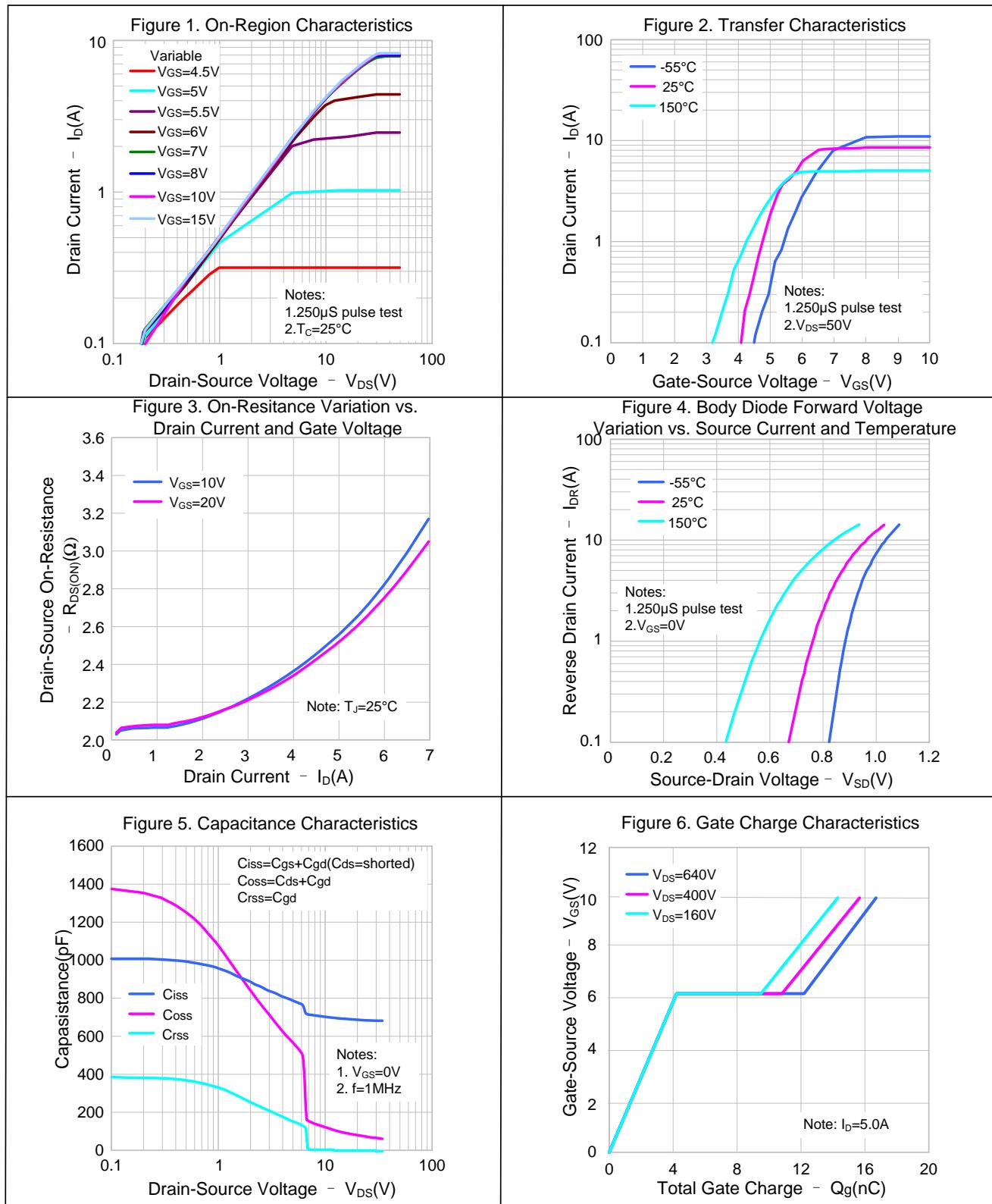
## SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I <sub>S</sub>	Integral Reverse P-N Junction Diode in the MOSFET	--	--	6.0	A
Pulsed Source Current	I <sub>SM</sub>		--	--	24	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =6.0A, V <sub>GS</sub> =0V	--	--	1.4	V
Reverse Recovery Time	T <sub>rr</sub>	I <sub>S</sub> =6.0A, V <sub>GS</sub> =0V, dI <sub>F</sub> /dt=100A/μS (Note4)	--	549	--	ns
Reverse Recovery Charge	Q <sub>rr</sub>		--	3.0	--	μC

### Notes:

1. L=30mH, I<sub>AS</sub>=4.5A, V<sub>DD</sub>=60V, R<sub>G</sub>=25Ω, starting temperature T<sub>J</sub>=25°C;
2. V<sub>DS</sub>=0~400V, I<sub>SD</sub><=6.0A, T<sub>J</sub>=25°C;
3. V<sub>DS</sub>=0~480V;
4. Pulse Test: Pulse width ≤300μs, Duty cycle≤2%;
5. Essentially independent of operating temperature.

## TYPICAL CHARACTERISTICS





## TYPICAL CHARACTERISTICS(CONTINUED)

Figure 7. Breakdown Voltage Variation vs. Temperature

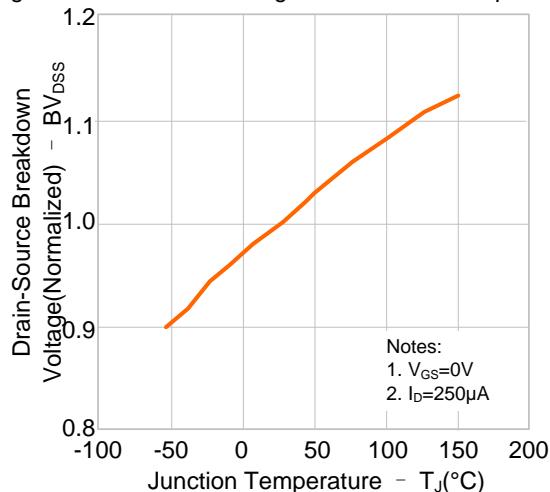


Figure 8. On-resistance Variation vs. Temperature

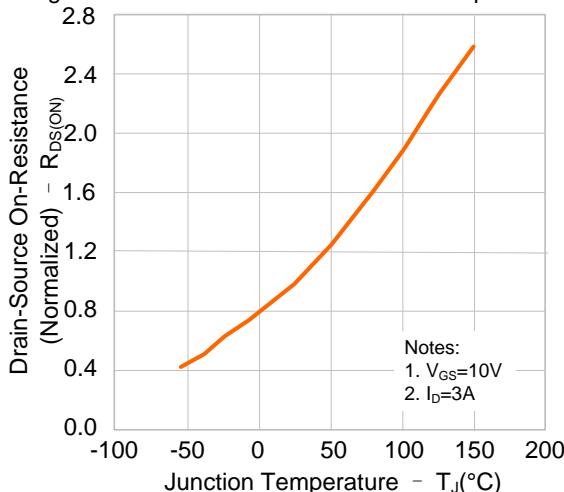


Figure 9-1. Max. Safe Operating Area(SVF6N80D/MJ)

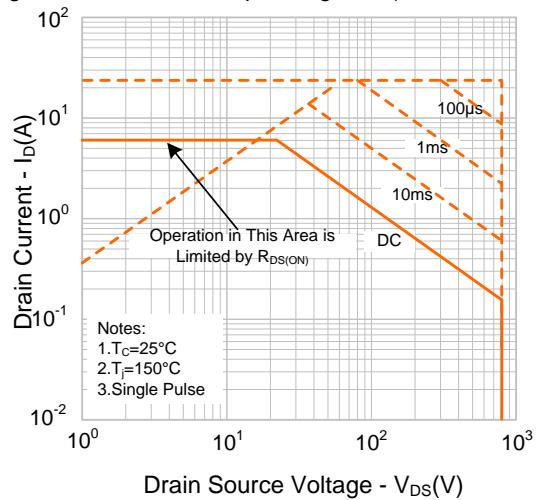


Figure 9-2. Max. Safe Operating Area(SVF6N80K)

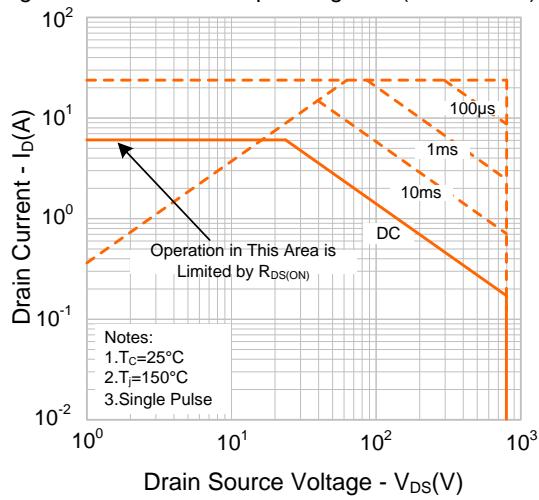
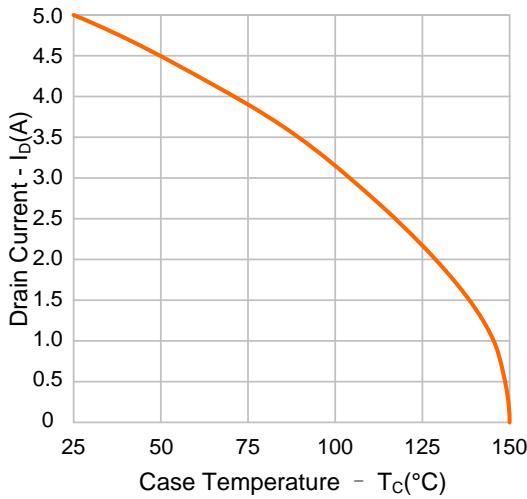
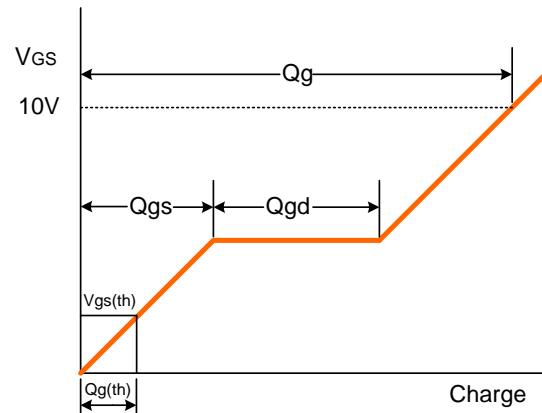
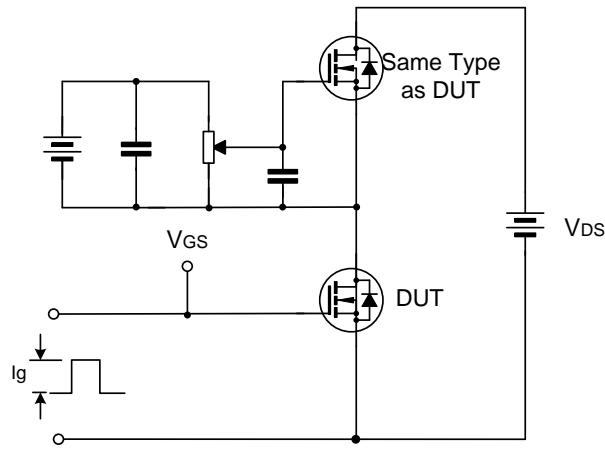


Figure 10. Maximum Drain Current vs. Case Temperature

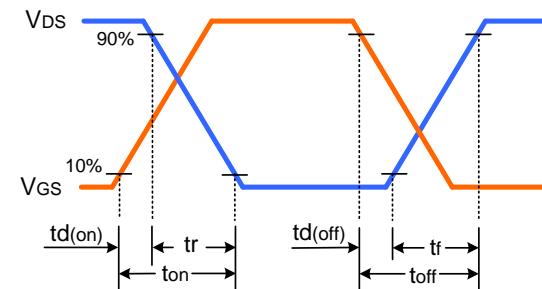
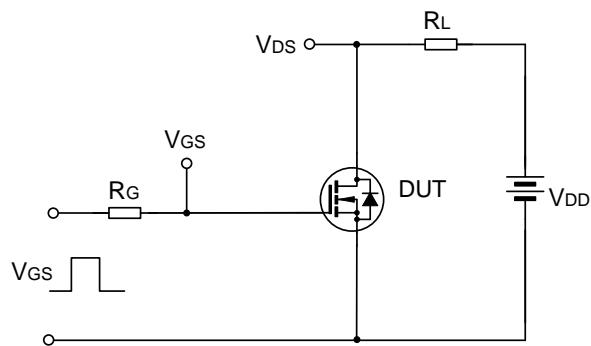


## TYPICAL TEST CIRCUIT

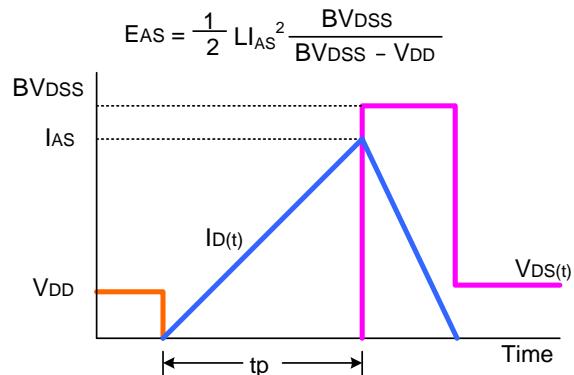
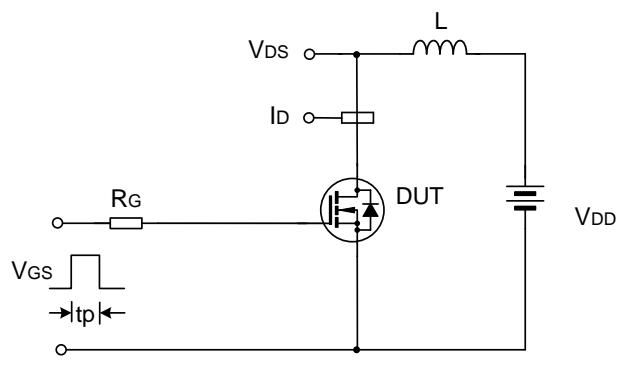
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveform

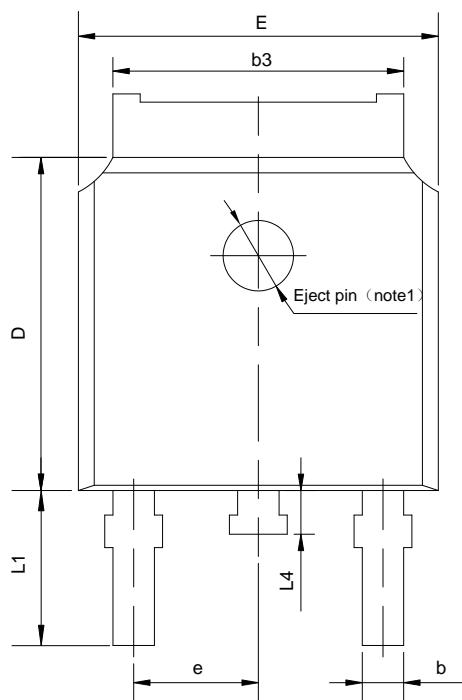




## PACKAGE OUTLINE

TO-252-2L

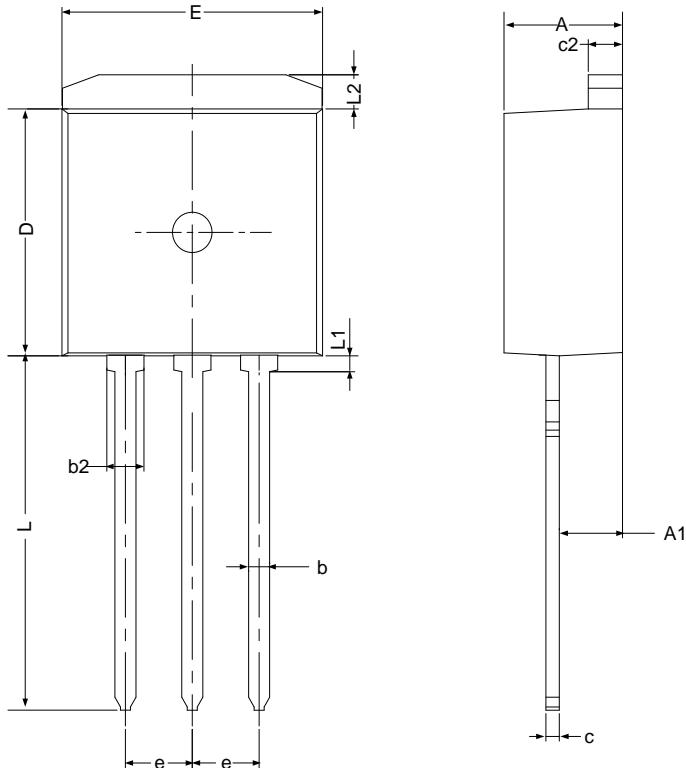
UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.10	2.30	2.50
A1	0	—	0.127
b	0.66	0.76	0.89
b3	5.10	5.33	5.46
c	0.45	—	0.65
c2	0.45	—	0.65
D	5.80	6.10	6.40
E	6.30	6.60	6.90
e	2.30TYP		
H	9.60	10.10	10.60
L	1.40	1.50	1.70
L1	2.90REF		
L4	0.60	0.80	1.00

TO-262-3L

UNIT: mm

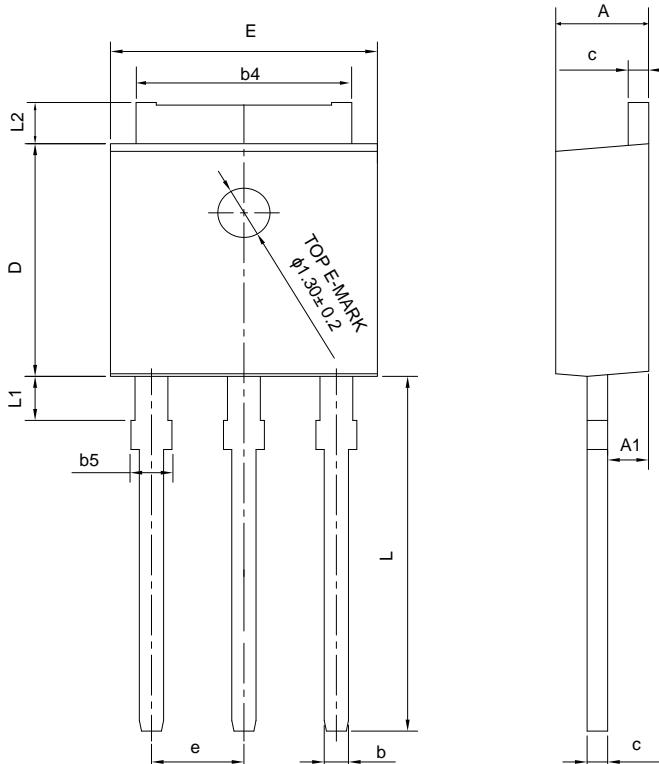


SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	2.20	—	2.92
b	0.71	0.80	0.90
b2	1.20	—	1.50
c	0.34	—	0.65
c2	1.22	1.30	1.35
D	8.38	—	9.30
E	9.80	10.16	10.54
e	2.54 BSC		
L	12.80	—	14.10
L1	—	—	0.75
L2	1.12	—	1.42



## PACKAGE OUTLINE

TO-251J-3L		UNIT: mm		
SYMBOL	MILLIMETER			
	MIN	NOM	MAX	
A	2.18	2.30	2.39	
A1	0.89	1.00	1.14	
b	0.56	—	0.89	
b4	4.95	5.33	5.46	
b5	—	—	1.05	
c	0.46	—	0.61	
D	5.97	6.10	6.27	
E	6.35	6.60	6.73	
e	2.29 BCS			
L	8.89	9.30	9.65	
L1	0.95	—	1.50	
L2	0.89	—	1.27	



### Important notice :

- The instructions are subject to change without notice! Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current.
- Our products are consumer electronic products, and / or civil electronic products.
- When using our products, please do not exceed the maximum rating of the products, otherwise the reliability of the whole machine will be affected. There is a certain possibility of failure or malfunction of any semiconductor product under specific conditions. The buyer is responsible for complying with safety standards and taking safety measures when using our products for system design, sample and whole machine manufacturing, so as to avoid potential failure risk that may cause personal injury or property loss.
- It is strongly recommended to identify the trademark when buying our products. Please contact us if there is any question.
- When exporting, using and reselling our products, buyer must comply with the international export control laws and regulations of China, the United States, the United Kingdom, the European Union and other countries & regions.
- Product promotion is endless, our company will wholeheartedly provide customers with better products!
- Website: <http://www.silan.com.cn>

---

Part No.:	SVF6N80D(K)	Document Type:	Datasheet
Copyright:	HANGZHOU SILAN MICROELECTRONICS CO.,LTD	Website:	<a href="http://www.silan.com.cn">http://www.silan.com.cn</a>

---

Rev.: 1.3

Revision History:

1. Add SVF6N80MJ
  2. Update the template of the datasheet
- 

Rev.: 1.2

Revision History:

1. Add Electrical schematic and TYPICAL TEST CIRCUIT
- 

Rev.: 1.1

Revision History:

1. Add SVF6N80K
- 

Rev.: 1.0

Revision History:

1. First release
-